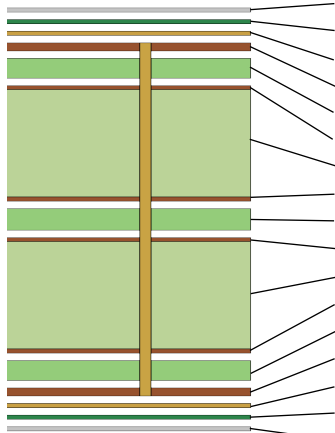


BOARD CHARACTERISTICS

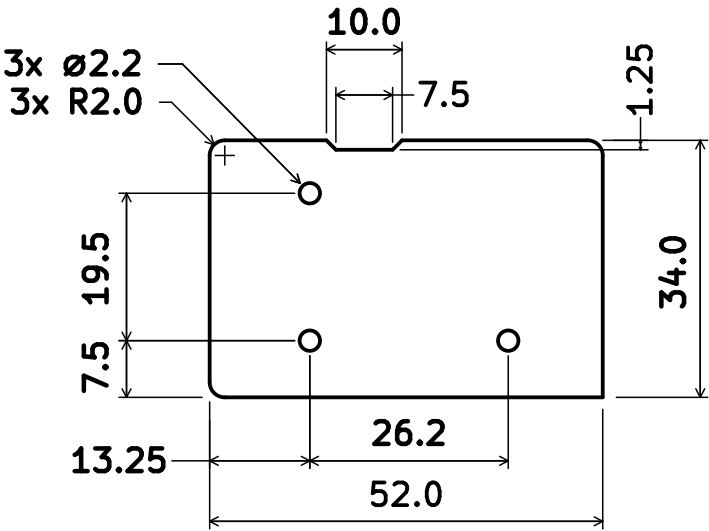
Copper Layer Count: 6 Board Thickness: 1.5384 mm  
Board overall dimensions: 52.0 mm x 34.0 mm  
Min track/spacing: 0.14 mm / 0.15 mm Min hole diameter: 0.20 mm  
Copper Finish: ENIG Impedance Control: Yes  
Castellated pads: No Plated Board Edge: No  
Edge card connectors: No



Layer Name	Type	Material	Thickness (mm)	Epsilon R
F.Silkscreen	Top Silk Screen			
F.Mask	Top Solder Mask			
	Top Surface Finish	ENIG		
L1 (Sig)	copper		0.035 mm	
Dielectric 1	prepreg	3313 RC57%	0.0994 mm	4.1
L2 (GND)	copper		0.0152 mm	
Dielectric 2	core	Core	0.55 mm	4.6
L3 (Sig)	copper		0.0152 mm	
Dielectric 3	prepreg	2116 RC54%	0.1088 mm	4.16
L4 (PWR)	copper		0.0152 mm	
Dielectric 4	core	Core	0.55 mm	4.6
L5 (GND)	copper		0.0152 mm	
Dielectric 5	prepreg	3313 RC57%	0.0994 mm	4.1
L6 (Sig)	copper		0.035 mm	
	Bottom Surface Finish	ENIG		
B.Mask	Bottom Solder Mask			
B.Silkscreen	Bottom Silk Screen			

Impedance control requirements (+/- 10%):

Coplanar 90-Ohm Differential (L1 ref L2)  
0.16mm width, 0.25mm spacing, 0.15mm to copper  
Coplanar 50-Ohm Single-Ended (L6 ref L5)  
0.15mm width, 0.15mm to copper  
Coplanar 50-Ohm Single-Ended (L6 ref L3)  
0.65mm width, 0.17mm to copper



ALL UNITS IN MILLIMETERS

SparrowTheNerd

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